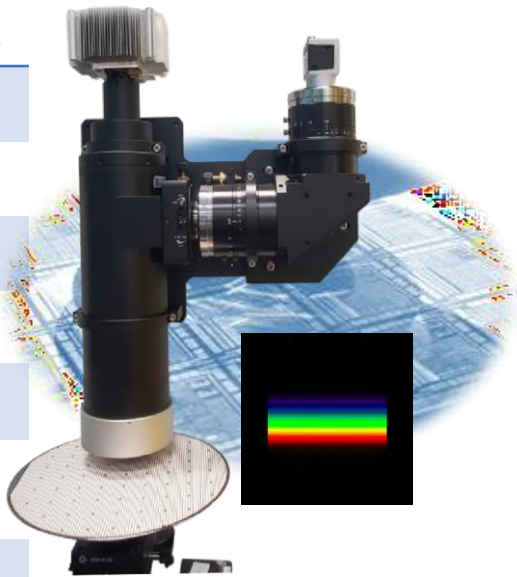


同轴共聚焦三维线扫描测量系统

Coaxial Confocal 3D Line Scanning System

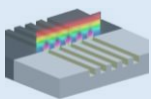
系统规格System Specifications

	产品1 Product 1	产品2 Product 2	产品3 Product 3	产品4 Product 4
视场 Field of View	11.26mm	11.26mm	11.26mm	20mm
XY分辨率 XY resolution	2.5μm	5.5μm	5.5μm	10μm
Z分辨率 Z resolution	0.5μm	2.5μm	1μm	10μm
支持最大物体倾斜角度 Max slope of obj.	±22deg	±22deg	±22deg	±15deg
最大深宽比 Max aspect ratio	≤8	≤8	≤8	≤15
最快扫描速度 100GigE (满屏) 40GigE Max scan speed	3,462线 2,100线	3,462线 2,100线	3,462线 2,100线	1,000线 457线
最快扫描速度 100GigE (1/8屏) 40GigE Max scan speed	24,500线 16,000线	24,500线 16,000线	24,500线 16,000线	8,000线 3,400线



同轴双远心光路 Co-axial telecentric

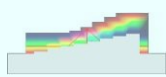
- 同轴光路+双远心设计
Coaxial, telecentric optical
- 适合深孔测量，避免阴影遮挡
Overcome shadow effect for deep hole



凹槽/深孔检测
Trough/deep hole inspection

高精度·亚微米级 High res. · Sub-microm

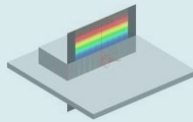
- 光谱共聚焦
Spectrum confocal
- 高分辨率光谱成像设计
High resolution spectrum sensing



凹台阶检测
Steps inspection

大视场·大扫描范围 Large FOV · Scan range

- 线扫描测量
Line scanning
- 视场可达20mm
FOV up to 20mm



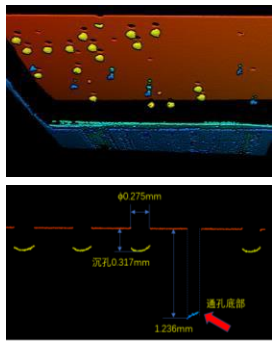
大范围测量
Large range scan

高速三维测量 High speed 3D scan

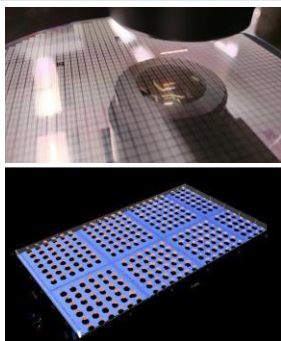
- 快速3D测量算法
3D metrology algorithm
- 匹配硬件加速
Hardware acceleration



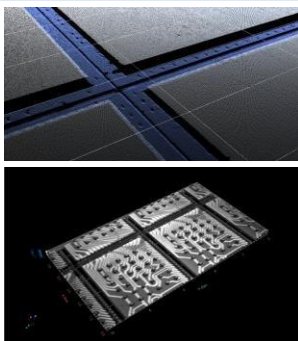
应用例子Application Examples



PCB深孔检测
PCB deep hole inspection



半导体3D IC:
晶圆凸块、重布线层，硅通孔检测
Semiconductor 3D IC:
wafer bump, RDL, TSV inspection



多层透明/闪亮物体检测
Multi-layers transparent / shiny objects inspection

